

MOS Field Effect Transistor

NP40N06CLC,NP40N06DLC,NP40N06ELC

N-CHANNEL MOS FIELD EFFECT TRANSISTOR FOR SWITCHING

DESCRIPTION

This product is N-channel MOS Field Effect Transistor designed for high voltage switching application.

FEATURES

- · Channel temperature 175dgree rated
- · Low On-state resistance

RDS(on)1= 0.027Ω MAX. at VGS= 10V, ID= 18A RDS(on)2= 0.04Ω MAX. at VGS= 4V, ID= 18A

- Low Ciss Ciss= 1000pF
- · High avalanche Capability Ratings
- · TO-220AB, TO-262AA, TO-220SMD Package

ORDERING INFORMATION

	1
PART NUMBER*	PACKAGE
NP40N06CLC	TO-220AB
NP40N06DLC	TO-262AA
NP40N06ELC	TO-220SMD

^{*:}Tentative Type Number

ABSOLUTE MAXIMUM RATINGS(T_A=2 5 ℃)

Drain to source Voltage	V _{DSS}	60	V
Gate to Source Voltage	V_{GSS}	±20	٧
Drain Current(DC)	I D(DC)	±40	A
Drain Current(pulse)	D(pulse)	±160 [*]	A
Total Power Dissipation	P _{T1}	84**	W
Total Power Dissipation	P _{T2}	1.5 ***	W
Single Avalanche Current	las	40 ****	Α
Single Avalanche Energy	Eas	T.B.D ***	* mJ
Channel Temperature	T ch	175	C
Storage Temperature	T stg	-55 to +175	C

^{*}PW≦10 μ s,Duty Cycle≤1%

The information in this document is subject to change without notice.

^{**}Tc=25℃, ***Ta=25℃

^{****} Starting Tch=25°C,RG=25Ω,VGS=20V→0

THERMAL RESISTANCE

Channel to Case

Rth(ch-c) 1.79°C/W

Channel to Ambient

Rth(ch-a)

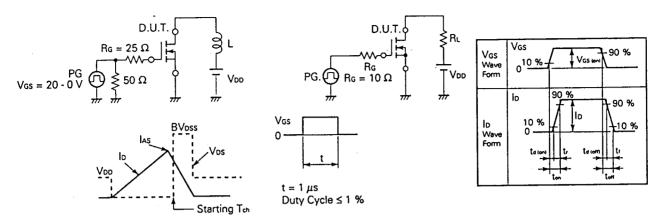
100°C/W

ELECTRICAL CHARACTERISTICS (T_A= 2 5 °C)

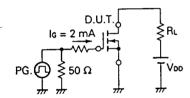
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CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Drain Cut-off Current	IDSS			10	μΑ	$V_{DS} = 60V, V_{GS} = 0$
Gate Leakage Current	IGSS			±10	μΑ	$V_{GS} = \pm 20V, V_{DS} = 0$
Gate Cut-off Voltage	V _{GS(off)}	1.0	1.5	2.0	V	$V_{DS} = 10V$, $I_D = 1mA$
Forward Transfer Admittance	y _{f s}	10	23		S	$V_{DS} = 10V$, $I_{D} = 18A$
Drain to Source On-State Resistance	R _{DS(on)1}		0.02	0.027	Ω	$V_{GS} = 10V, I_D = 18A$
Drain to Source On-State Resistance	R _{DS(on)2}		0.033	0.04	Ω	V _{GS} = 4V, I _D = 18A
Input Capacitance	Ciss		1000	1500	pF	V _{DS} = 25V
Output Capacitance	Coss		400	600	pF	V _{G S} =0
Reverse Transfer Capacitance	C , s s		150	270	pF	f =1MHz
Turn-on Delay Time	t d(on)		35	T.B.D.	ns	V _{DD} = 30V, I _D = 18A
Rise Time	t,		280	T.B.D.	ns	$V_{GS(on)} = 10V, R_{G} = 10\Omega$
Turn-off Delay Time	t d(off)		160	T.B.D.	ns	R _L =1.67 Ω
Fall Time	t _f	**************************************	170	T.B.D.	ns	
Total Gate Charge	Q _G		50	T.B.D.	nC	V _{DS} = 48V
Gate to Source Charge	Q _{GS}		4.5		nC	V _{G S} = 10V
Gate to Drain Charge	Q _{GD}		22		nC	I _D = 35A
Diode Forward Voltage	V _{F(S-D)}		1.0		٧	I _F = 35A, V _{GS} =0
Reverse Recovery Time	t,,		70.		ns	I _F = 35A, V _{GS} =0
Reverse Recovery Charge	α,,		130		nC	di/dt= 100A/ μs

Test Circuit 1 Avalanche Capability

Test Circuit 2 Switching Time



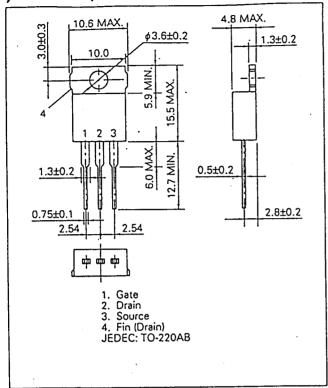
Test Circuit 3 Gate Charge



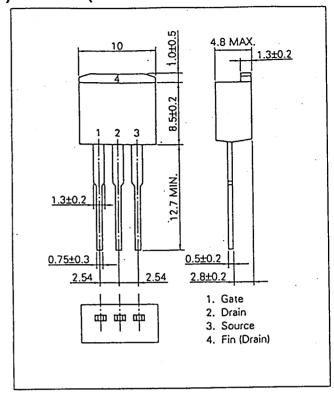
The application circuits and their parameters are for references only and are not intended for use in actual design-in's.

Package Dimensions(in millimeter)

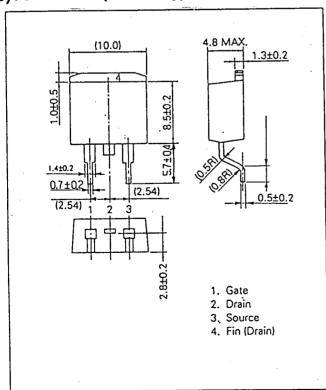
1)TO-220AB(MP-25)



2)TO-262AA(TO-220 Fin Cut:MP-25 Fin Cut)



3)TO-220SMD(JEDEC type:MP-25ZJ)



The information contained in this document is being issued in advance of the production cycle for the device. The parameters for the device may change before final production or NEC Corporation, at its own discretion, may withdraw the device prior to its production.

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Anti-radioactive design is not implemented in this product.